

Product Texts

Zytel® HTN high performance polyamide resins feature high retention of properties upon exposure to elevated temperature, to high moisture, and to harsh chemical environments. Polymer families and grades of Zytel® HTN are tailored to optimize performance as well as processability.

Typical applications with Zytel® HTN include demanding applications in the automotive, electrical and electronics, domestic appliances, and construction industries.

Zytel® HTNFR52G30BL BK337 is a 30% glass reinforced, flame retardant, lubricated high performance polyamide resin that has been developed for connector applications.

Processing/Physical Characteristics	dry / cond	Unit	Test Standard
ISO Data			
^[C] Molding shrinkage, parallel	0.3 / *	%	ISO 294-4, 2577
^[C] Molding shrinkage, normal	0.8 / *	%	ISO 294-4, 2577

[C]: CAMPUS

Mechanical properties	dry / cond	Unit	Test Standard
ISO Data			
^[C] Tensile Modulus	11800 / -	MPa	ISO 527
^[C] Stress at break	160 / -	MPa	ISO 527
^[C] Strain at break	2 / -	%	ISO 527
^[C] Charpy impact strength, +23°C	50 / 35	kJ/m ²	ISO 179/1eU
^[C] Charpy impact strength, -30°C	40 / 35	kJ/m ²	ISO 179/1eU
^[C] Charpy notched impact strength, +23°C	10 / -	kJ/m ²	ISO 179/1eA
^[C] Charpy notched impact strength, -30°C	10 / -	kJ/m ²	ISO 179/1eA

[C]: CAMPUS

Thermal properties	dry / cond	Unit	Test Standard
ISO Data			
^[C] Glass transition temperature, 10°C/min	90 / *	°C	ISO 11357-1/-2
^[C] Temp. of deflection under load, 1.80 MPa	282 / *	°C	ISO 75-1/-2
^[C] Coeff. of linear therm. expansion, parallel	20 / *	E-6/K	ISO 11359-1/-2
^[C] Coeff. of linear therm. expansion, normal	63 / *	E-6/K	ISO 11359-1/-2
^[C] Burning Behav. at 1.5 mm nom. thickn.	V-0 / *	class	IEC 60695-11-10
Thickness tested	1.5 / *	mm	-
Yellow Card available	yes / *	-	-
^[C] Burning Behav. at thickness h	V-0 / *	class	IEC 60695-11-10
Thickness tested	3.0 / *	mm	-
Yellow Card available	yes / *	-	-
^[C] Burning Behav. 5V at thickness h	5VA / *	class	IEC 60695-11-20
Thickness tested	1.5 / *	mm	-
Yellow Card available	yes / *	-	-
^[C] Oxygen index	42 / *	%	ISO 4589-1/-2

[C]: CAMPUS

Electrical properties	dry / cond	Unit	Test Standard
ISO Data			
^[C] Relative permittivity, 100Hz	3.5 / -	-	IEC 62631-2-1
^[C] Relative permittivity, 1MHz	3.3 / -	-	IEC 62631-2-1
^[C] Dissipation factor, 100Hz	50 / -	E-4	IEC 62631-2-1
^[C] Dissipation factor, 1MHz	135 / -	E-4	IEC 62631-2-1
^[C] Volume resistivity	>1E13 / -	Ohm*m	IEC 62631-3-1

[C]: CAMPUS

Other properties	dry / cond	Unit	Test Standard
^[C] Density	1620 / -	kg/m ³	ISO 1183

[C]: CAMPUS

Characteristics**Processing**

Injection Molding

Chemical Resistance

General Chemical Resistance

Additives

Lubricants

Applications

Automotive, Electrical and Electronical

Special Characteristics

Flame retardant, Heat stabilized or stable to heat

Regional Availability

North America, Europe, Asia Pacific, South and Central America

Other text information**Injection molding**

During molding, use proper protective equipment and adequate ventilation. Avoid exposure to fumes and limit the holdup time and temperature of the resin in the machine. Purge degraded resin carefully with HDPE.